

SOT1941-1

FBGA780, plastic, fine-pitch ball grid array; 780 balls, 0.65 mm pitch, 19 mm x 19 mm x 2.37 mm body

24 October 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA780
Package type industry code	FBGA780
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-9-2017
Manufacturer package code	98ASA01114D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	19	-	mm
E	package width	-	-	19	-	mm
A	seated height	-	-	2.37	-	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	780	-	A/A



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2. Package outline

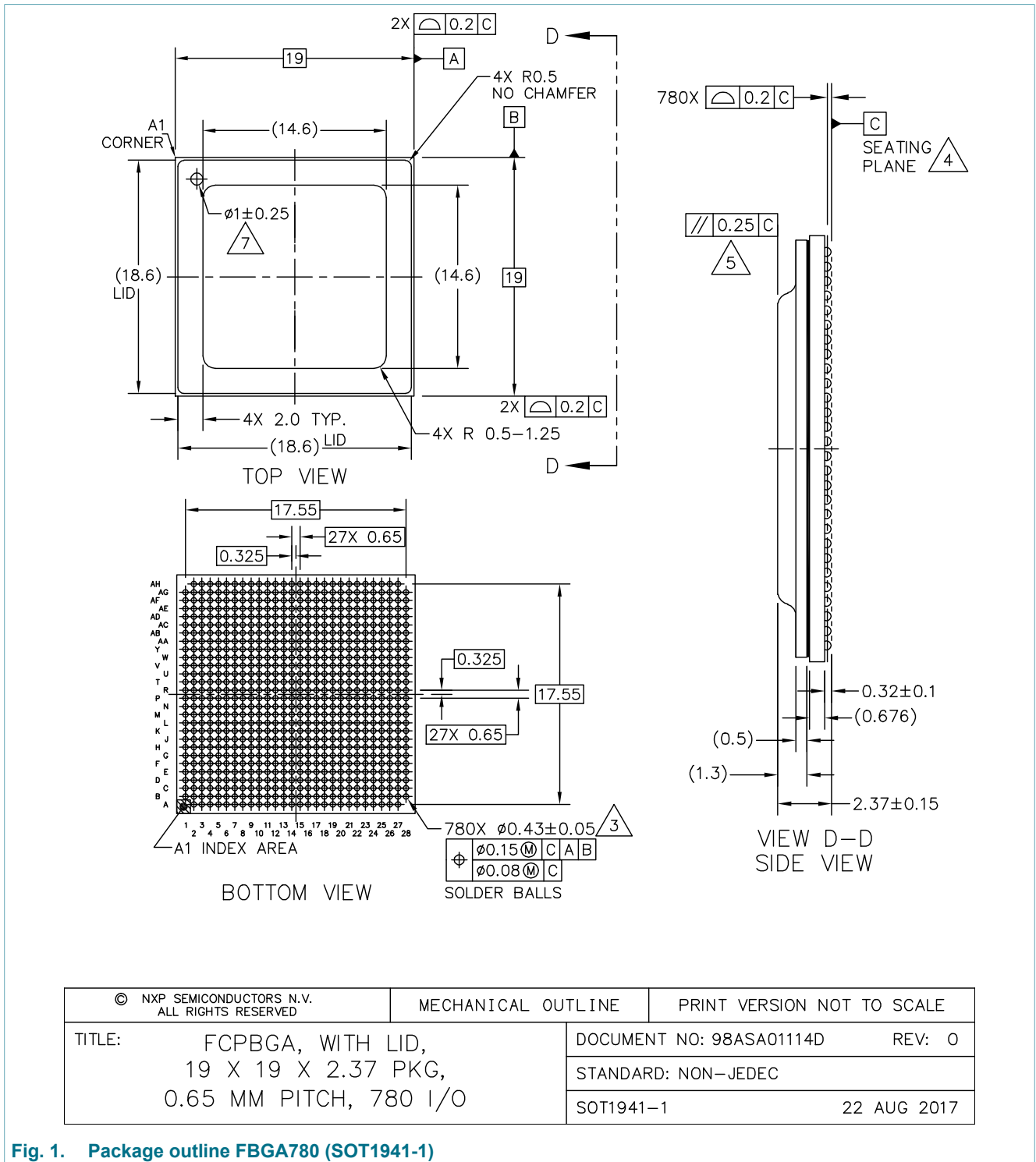


Fig. 1. Package outline FBGA780 (SOT1941-1)

FBGA780, plastic, fine-pitch ball grid array; 780 balls, 0.65 mm pitch, 19 mm x 19 mm x 2.37 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C. RAW BALL DIAMETER IS 0.4MM.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN THE FOOT AREA.
8. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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TITLE: FCPBGA, WITH LID, 19 X 19 X 2.37 PKG, 0.65 MM PITCH, 780 I/O	DOCUMENT NO: 98ASA01114D	REV: 0	
	STANDARD: NON-JEDEC		
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Fig. 2. Package outline note FBGA780 (SOT1941-1)

3. Legal information

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